



Thermal Pad KB5100S

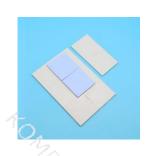
Thermal pads are used to fill the air gap between a heat generating device and a heat sink or metal base. Their flexible and elastic characteristics enable them to be used to cover very uneven surfaces. Heat is conducted from a separate device or the entire PCB to a metal housing or diffusion plate, thereby increasing the efficiency and service life of the heat generating electronic components.

Performance parameter table

| Series | color | Thermal Conductivity (W/m*K) | Hardness (Shore 00) | Thickness (mm) | Density (g/cm3) | Dielectric strength (KV/mm) | Fire Rating | Volume Resistivity (Ω· cm) |
|---------|----------------|------------------------------|---------------------|----------------|-----------------|-----------------------------|----------------|----------------------------------|
| KB5110S | custom made | 1.0±0.5 | 40~70 | 0.55.0 | 2.60±0.05 | ≥12 | UL94- V 0 | ≥10 ¹³ |
| KB5120S | custom made | 2.0±0.5 | 40~70 | 0.55.0 | 2.83±0.05 | ≥12 | UL94- V 0 | ≥10 ¹³ |
| KB5130S | custom made | 3.0±0.5 | 40~70 | 0.55.0 | 3.05±0.05 | ≥12 | UL94- V 0 | ≥10 ¹³ |
| KB5140S | custom made | 4.0±0.5 | 40~70 | 0.55.0 | 3.23±0.05 | ≥12 | UL94- V 0 | ≥10 ¹³ |
| KB5150S | custom made | 5.0±0.5 | 40~70 | 1.05.0 | 3.40±0.05 | ≥12 | UL94- V 0 | ≥10 ¹³ |







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The structure diagram is as follows

| 序号/N0 | | 材料 /Layer & Mate | erial | 备注/Remark | | |
|-------|-----------|------------------|---------------|-----------------------|--|--|
| 1 | | | Base film | 50 μm Released film | | |
| 2 | 9 | | Glue | Acylic B side | | |
| 3 | Structure | | Base material | 25 um Released film | | |
| 4 | | | Glue | Silicome foam B side | | |
| 5 | | | Bottom film | Fluorine release film | | |

Specific features:

- 1. The tape is self-adhesive and does not require additional surface adhesives and adhesive backing. It has good elasticity and recovery and can adapt to pressure changes and temperature fluctuations.
- 2. It has good heat conduction effect, effectively protecting the life and safety of the working body
- 3. Different thickness and size options can be provided according to actual application
- 4. Good processing performance, easy installation and pressing, no adhesion to the sealing surface, easy to disassemble
- 5. Low hardness, good compliance, low stress, more effective protection of electrical components
- 6. Excellent high and low temperature resistance, chemical and mechanical stability, weather resistance, radiation resistance and dielectric properties
- 7. Applicable to all electronic, medical, battery, mobile phone, computer and other industries that require heat dissipation, such as computer storage chips, display driver IC, CD-ROM/DVD, LCD TV backlight unit, communication equipment between CPU and radiator, etc.

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